

Dual P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY

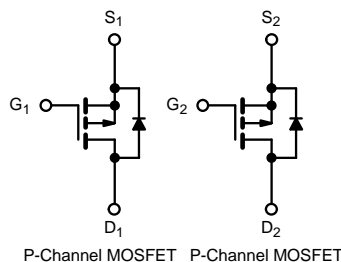
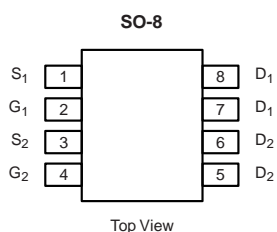
V_{DS} (V)	- 30
$R_{DS(on)}$ (Ω) at $V_{GS} = -10$ V	0.042
$R_{DS(on)}$ (Ω) at $V_{GS} = -4.5$ V	0.055
I_D (A) per leg	-6.6
Configuration	Dual

FEATURES

- TrenchFET® Power MOSFET
- AEC-Q101 Qualified^c
- 100 % R_g and UIS Tested



RoHS
COMPLIANT
HALOGEN
FREE



ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	- 6.6	A
	$T_C = 125^\circ\text{C}$		- 3.8	
Continuous Source Current (Diode Conduction)		I_S	- 3	
Pulsed Drain Current ^a		I_{DM}	- 26	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	- 17	
Single Pulse Avalanche Energy		E_{AS}	14	mJ
Maximum Power Dissipation ^a	$T_C = 25^\circ\text{C}$	P_D	3.3	W
	$T_C = 125^\circ\text{C}$		1.1	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^b	R_{thJA}	110	$^\circ\text{C}/\text{W}$
Junction-to-Foot (Drain)		R_{thJF}	45	

Notes

- Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.

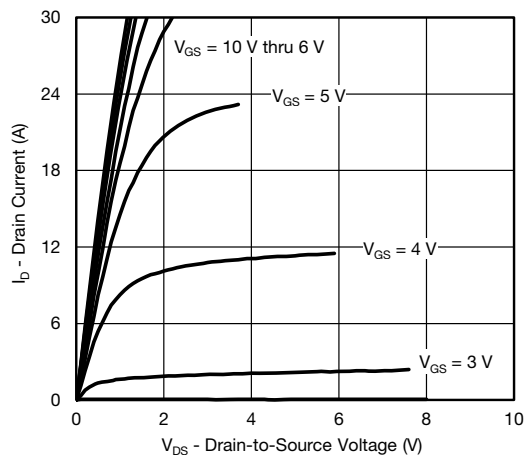
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 30	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 0.5	- 1.0	- 2.0	
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = - 30 V	-	-	- 1	μA
		V _{GS} = 0 V	V _{DS} = - 30 V, T _J = 125 °C	-	-	- 50	
		V _{GS} = 0 V	V _{DS} = - 30 V, T _J = 175 °C	-	-	- 150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 10 V	V _{DS} ≤ - 5 V	- 20	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 3.9 A	-	0.042	0.047	Ω
		V _{GS} = - 10 V	I _D = - 3.9 A, T _J = 125 °C	-	-	0.066	
		V _{GS} = - 10 V	I _D = - 3.9 A, T _J = 175 °C	-	-	0.076	
		V _{GS} = - 4.5 V	I _D = - 2.7 A	-	0.055	0.061	
Forward Transconductance ^b	g _{fs}	V _{DS} = - 15 V, I _D = - 4.9 A		-	9	-	S
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = - 25 V, f = 1 MHz	-	557	670	pF
Output Capacitance	C _{oss}			-	126	190	
Reverse Transfer Capacitance	C _{rss}			-	90	115	
Total Gate Charge ^c	Q _g	V _{GS} = - 10 V	V _{DS} = - 15 V, I _D = - 4.9 A	-	15	22	nC
Gate-Source Charge ^c	Q _{gs}			-	2.1		
Gate-Drain Charge ^c	Q _{gd}			-	3.5	-	
Gate Resistance	R _g	f = 1 MHz		2.60	5.26	8.50	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = - 15 V, R _L = 6.8 Ω I _D ≅ - 1 A, V _{GEN} = - 10 V, R _g = 1 Ω		-	3	5	ns
Rise Time ^c	t _r			-	9	14	
Turn-Off Delay Time ^c	t _{d(off)}			-	20	30	
Fall Time ^c	t _f			-	9	14	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	- 26	A
Forward Voltage	V _{SD}	I _F = - 2 A, V _{GS} = 0 V		-	- 0.8	- 1.2	V

Notes

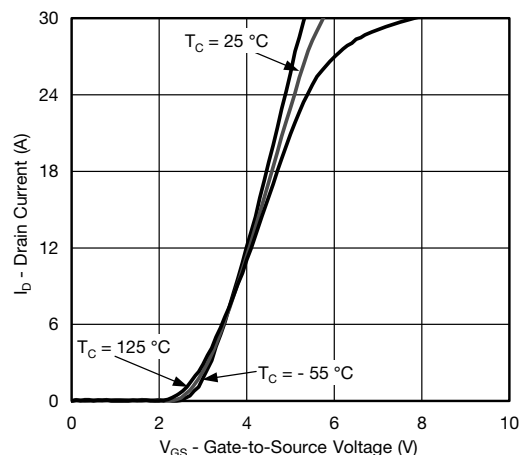
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

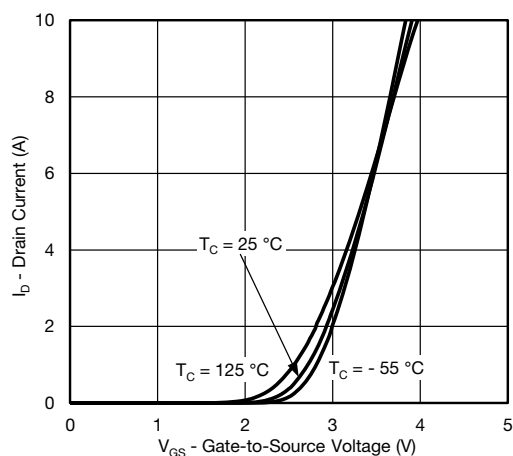
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



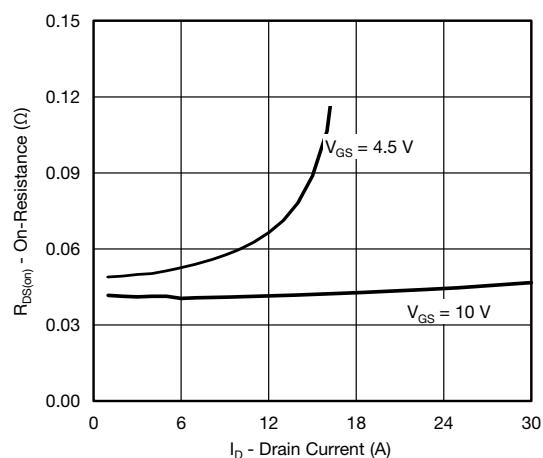
Output Characteristics



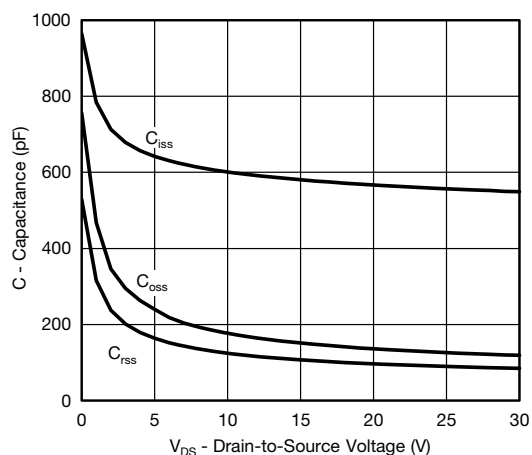
Transfer Characteristics



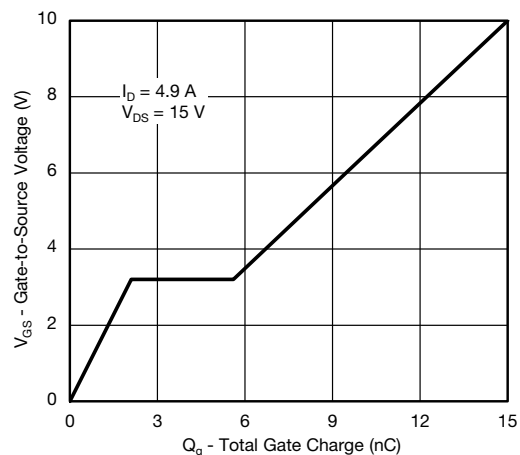
Transfer Characteristics



On-Resistance vs. Drain Current

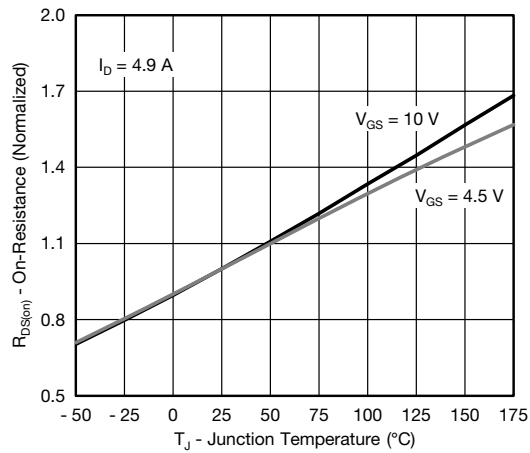


Capacitance

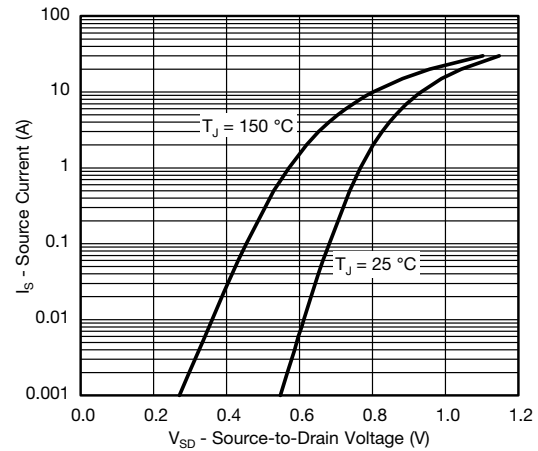


Gate Charge

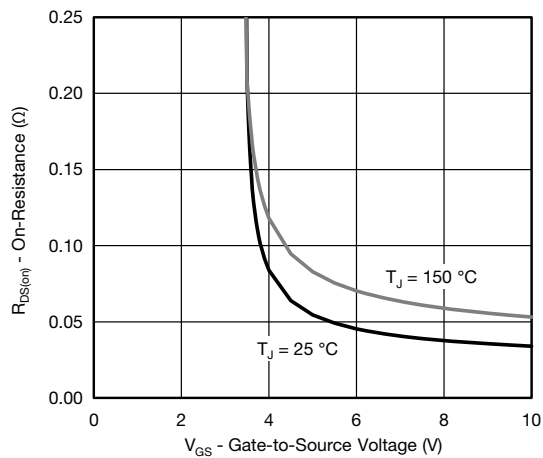
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



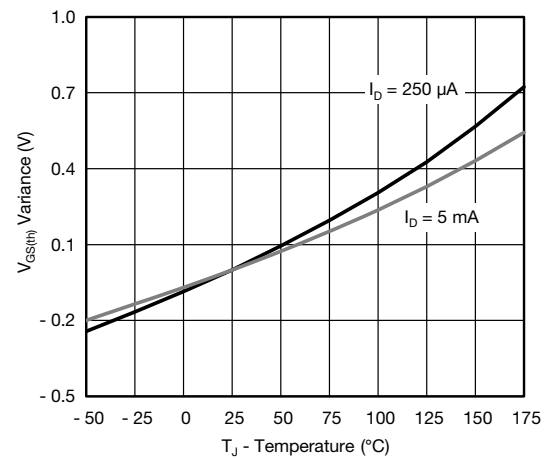
On-Resistance vs. Junction Temperature



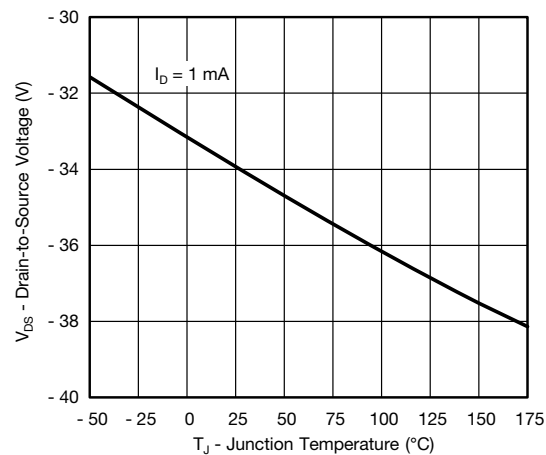
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

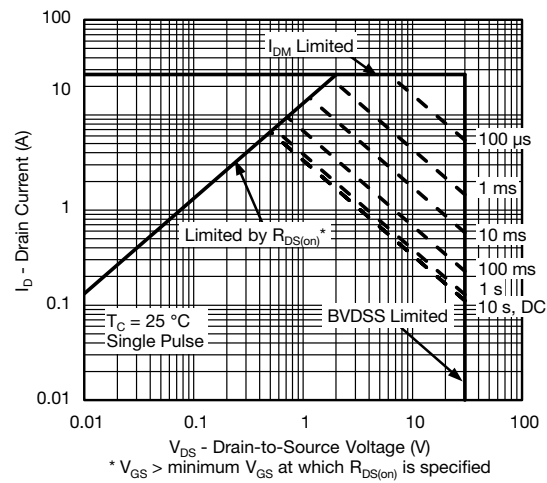


Threshold Voltage

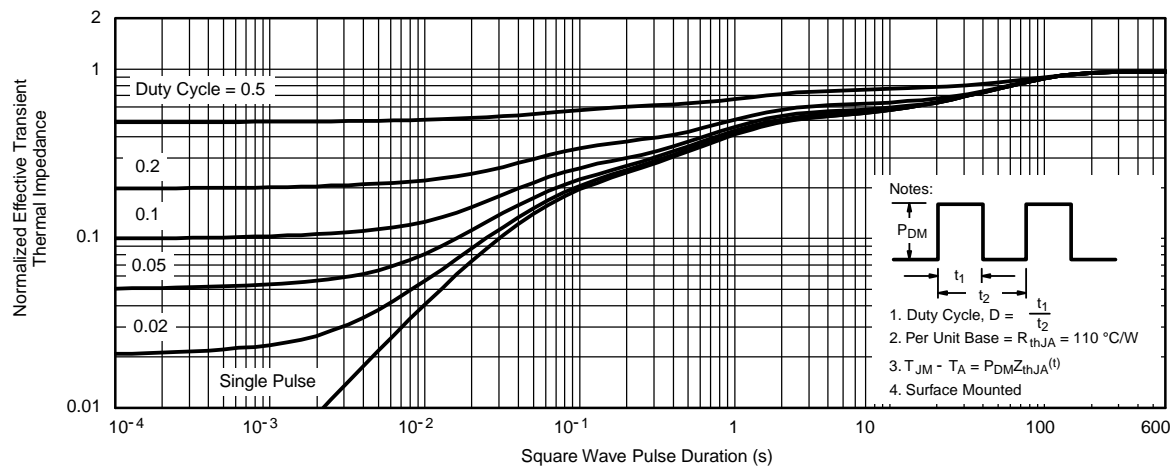


Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

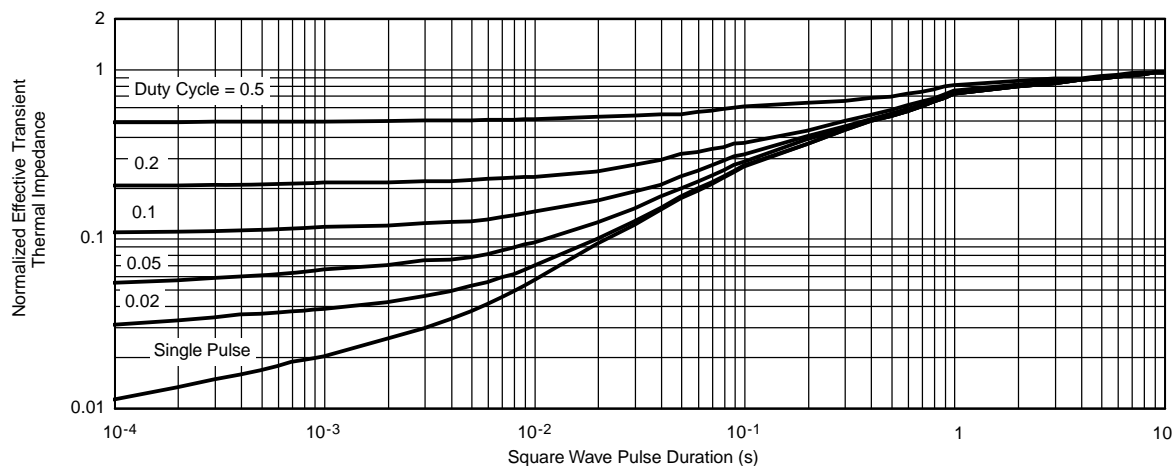


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

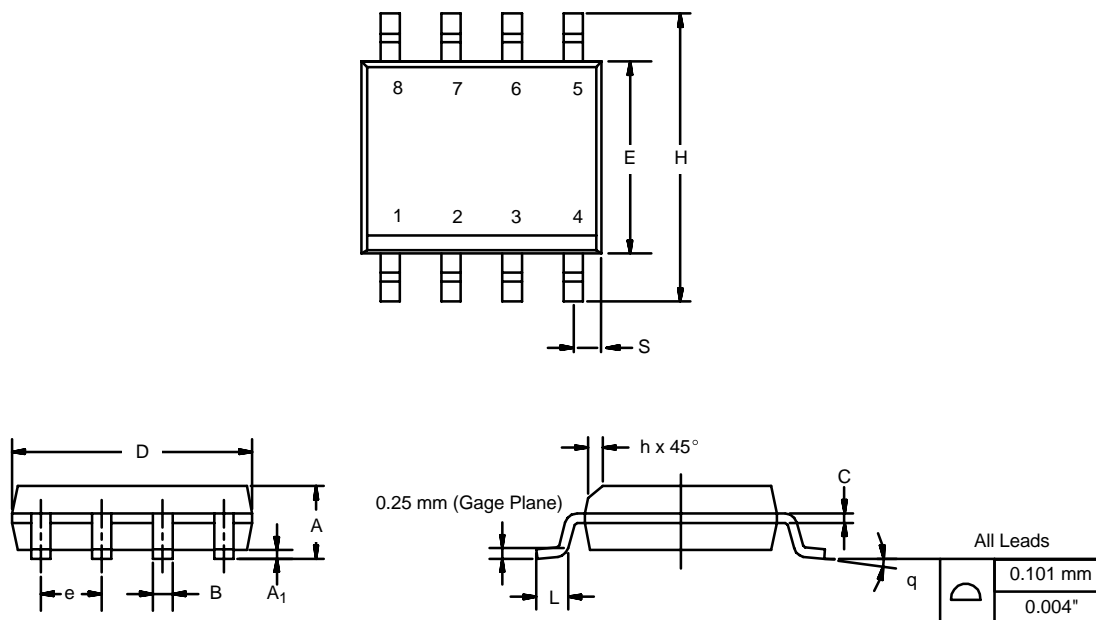


Normalized Thermal Transient Impedance, Junction-to-Foot

Note

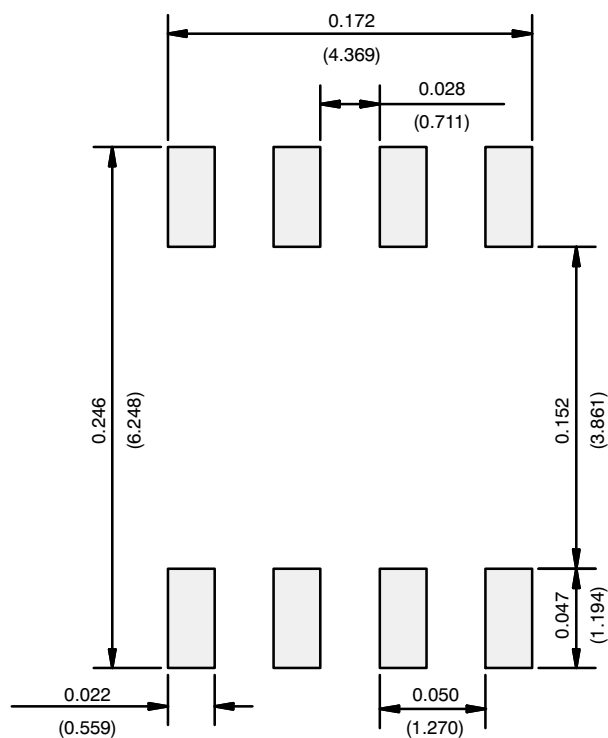
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Foot ($25\text{ }^{\circ}\text{C}$)
 are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

SOIC (NARROW): 8-LEAD
JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A ₁	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06				
DWG: 5498				

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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